

Ignition Gate Driver IC

Preliminary Document **FAD1101B-F085**



The FAD1101B-F085 is designed to directly drive an ignition IGBT and control the current and spark event of the coil. The coil current is controlled via the input pin. When the input is driven high, the output of the FAD1101B-F085 is enabled to turn on the IGBT and start charging the coil.

An input spike filter suppresses input signals of less than 13 μ s in duration. A Max Dwell timer is included in the FAD1101B-F085 which will turn off the IGBT if the input stays active for longer than the programmed time. This time interval can be modified through an external capacitor on the Max dwell pin. When the Max Dwell timer is exceeded, the FAD1101B-F085 will enter a Hard-Shut-Down mode quickly shutting off the collector current. The FAD1101B-F085 will also limit the collector current of the IGBT to $I_{c(lim)}$ during charging. This again is done through the sense resistor in the emitter leg of the Ignition IGBT developing a signal input to the Vsense pin of the FAD1101B-F085. The collector current level is relayed to the ECU via a current flag output.

Features

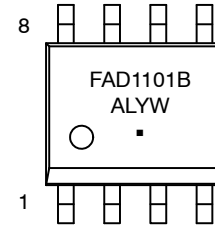
- Signal Line Input Buffer
- Input Spike Filter
- Ground Shift Tolerance ± 1.5 V
- Programmable Maximum Dwell Time
- Current Flag Output
- Control IGBT Current Limiting through Vsense Pin
- Hard Shutdown following Max Dwell Time Out
- This Device is Pb-Free and is RoHS Compliant

Typical Applications

- Switch on Coil

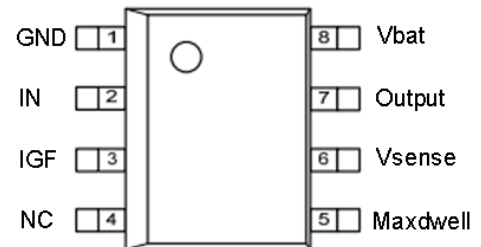
This Preliminary document is for informational purposes only. **onsemi** may update or withdraw it without notice. Content and referenced products are under development and subject to change.

MARKING DIAGRAM



- FAD1101B = Specific Device Code
 AL = Assembly Lot Code
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

PIN CONNECTIONS



ORDERING INFORMATION

Device	Package	Shipping [†]
FAD1101B-F085	SOIC8 (Pb-Free)	2500 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

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RECOMMENDED EXTERNAL COMPONENTS

Component	Description	Vendor	Parameter	Typ.	Unit
R _{BAT}	Limits transient currents during load dump		R	200 to 300	Ω
C _{BAT1}	Battery or Ignition voltage filtering		C	0.47	μF
C _{BAT}	Battery noise transients		C	100	nF
C _{IN}	Noise immunity		C	10	nF
C _{IGF}	Noise filter		C	10	nF
R _{SENSE}	Sense the collector current		R	18	mΩ

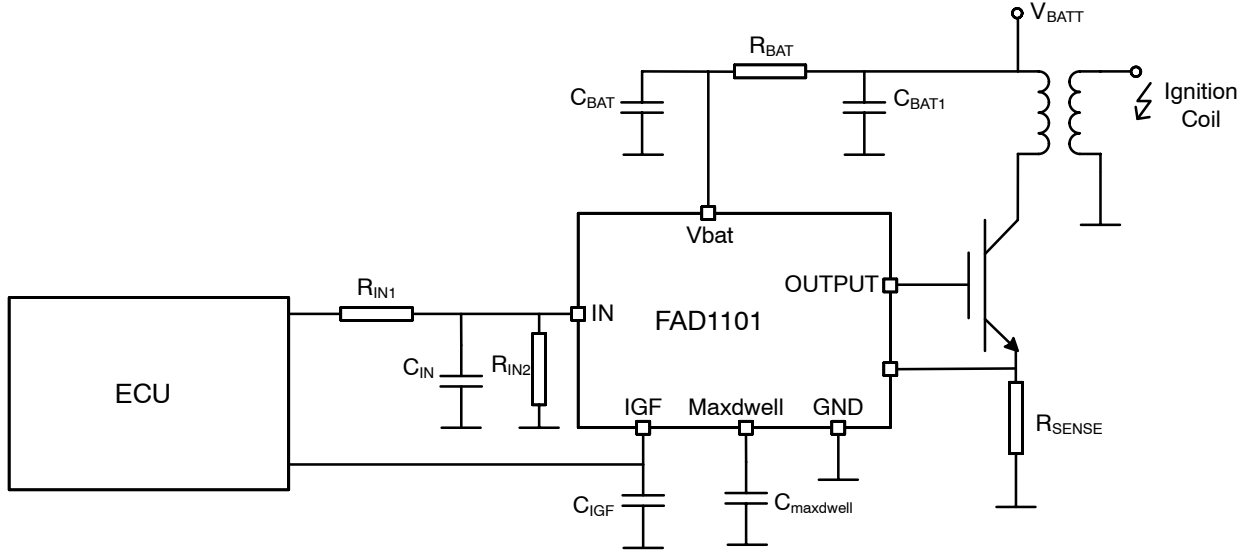


Figure 1. Typical Application Schematic

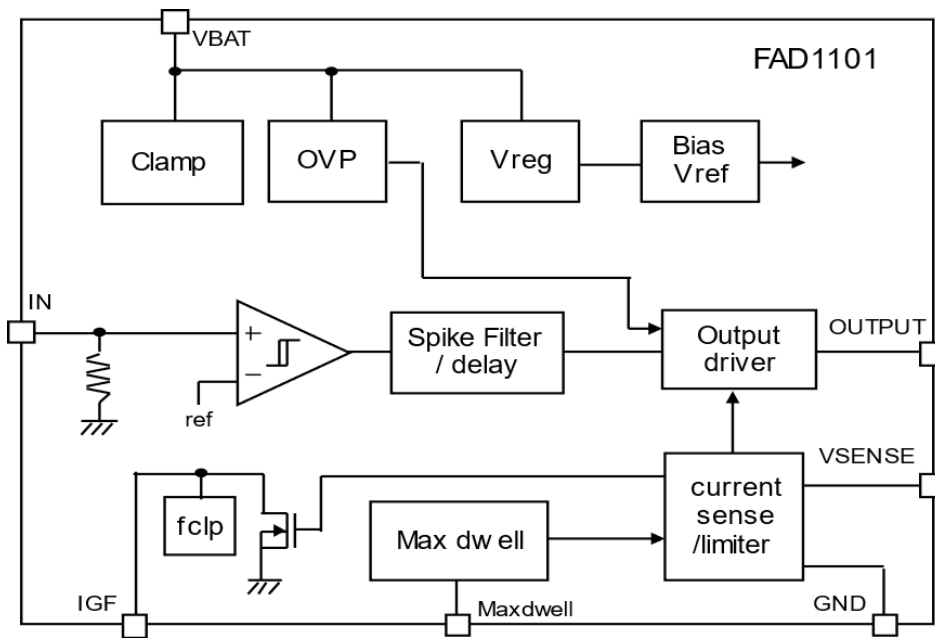


Figure 2. Simplified Block Diagram

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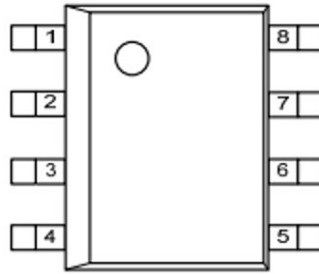


Figure 3. Pin Assignment (Top View)

PIN FUNCTION DESCRIPTION

Name	Type	Description
Pin1	GND	Ground reference of the IC
Pin2	IN	Input signal
Pin3	IGF	Collector Current Flag diagnosis and feedback signal
Pin4	NC	Connect to GND or floating
Pin5	Maxdwell	External Maxdwell cap to adjust the Maxdwell time
Pin6	V _{SENSE}	Sense Input used for Ilim function
Pin7	Output	Gate Drive to the IGBT
Pin 8	V _{BAT}	Supply voltage

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C unless otherwise specified)

Symbol	Parameter	Min.	Max.	Unit
V _{BAT}	Voltage at V _{BAT} pin (excl. EMC transients)	-0.3	28	V
V _{IN}	Voltage at Input pin with external R _{IN}	-2	16	V
V _{CSSD}	Voltage at C _{SSD} and Output pins	-0.3	3.6	V
V _{OUTPUT}	Voltage at Gate Output	-0.3	6.5	V
V _{SENSE}	Voltage on V _{SENSE} pin	0	400	mV
T _A	Maximum Ambient Operating Temperature	-40	150	°C
T _{STG}	Storage Temperature Range	-55	150	°C
P _{MAX}	Maximum continuous power dissipation at T _A = 25 °C		0.625	W
R _{θJA}	Thermal Resistance Junction-to-Ambient (Note 1)		200	°C /W
ESD _{HBM}	Electrostatic Discharge Voltage Capability, Human Body Model (Note 2)		2	kV
T _{SLD}	Lead Temperature Soldering (Note 3)		260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to the following standards
 - JESD51-2: Integral circuits thermal test method environmental conditions – natural convection
 - JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages
2. This device series incorporates ESD protection and is tested by the following methods
 - ESD Human Body Model tested per EIA/JESD22-A114
3. For information, please refer to our Soldering and Mounting Techniques Reference Manual, SOLDERRM/D
 - Reflow (SMD Styles Only), Pb-Free Versions

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RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristic	Min.	Typ.	Max.	Unit
V _{BAT}	Voltage at Vbat pin		14		V
V _{IN}	Voltage at Input pin		5		V
V _{IGF}	Voltage at IGF pin		5		V
Freq	Operating frequency			200	Hz
Rload	Load Resistance (for delay time measurements)		16		kΩ

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS

V_{BAT} = 6 to 28 V ; T_J = -40 °C to 150 °C (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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POWER SUPPLY CONDITIONS

V _{BAT1}	Operating voltage	Coil switching function only	4		28	V
V _{BAT2}	Operating voltage	All functions	6		28	V
I _{BAT}	Supply current	T _J = 150 °C, V _{BAT} = 28 V, Input = 5 V			5	mA
V _{CLAMP}	Battery clamp voltage	I _{BAT} = 10 mA	33		40	V

SENSE PIN CONDITIONS

V _{LIMIT}	Sense Voltage threshold at current limit	V _{BAT} > 8 V	185		215	mV
		6 V < V _{BAT} < 8 V	170			
I _{SENSE}	Current sourced out of V _{SENSE} pin			50	70	μA

INPUT CONTROL CONDITIONS

V _{INL}	Input low voltage		1.2	1.5	1.7	V
V _{INH}	Input high voltage		1.5	1.8	2.0	V
V _{INHys}	Input voltage hysteresis			0.3		V
T _{SPIKE}	Input spike filter	Delay on rising and falling edge of Input		13		μs
T _{ON}	Turn on delay time	50% at the input to 10% change at the output		15		μs
T _{OFF}	Turn off delay time	50% at the input to 10% change at the output		15		μs
R _{IN}	Input Impedance	V _{IN} = 0 to 5 V	230	310	400	Ω
		V _{IN} = 0 to 6 V	220		410	

GATE OUTPUT VOLTAGE MAX

V _{OUTPUT(MAX)}	Max Gate Output Voltage	16 KΩ pulldown resistor	4.5	5.25	6	V
V _{OUTPUT(LOW)}	Min Gate Output Voltage	0 mA < I _{GATE} < 0.4 mA at T _A = 25 °C	0.0		0.4	V

IGF

VGF _H	Collector Current flag High Sense Trigger Voltage		73	90	101	mV
VGF _L	Collector Current flag Low Sense Trigger Voltage		34	47	65	mV
IGF _H	Collector Current flag High	Sense Resistor 18 mΩ (resistance tolerance not included)	4.1	5.0	6.4	A
IGF _L	Collector Current flag Low	Sense Resistor 18 mΩ (resistance tolerance not included)	1.9	2.6	3.6	A
V _{FCLAMP}	Flag Clamp Voltage	I = 12 mA		25		V
R _{FCLAMP}	Flag Clamp Resistance	Flag = 1 V	30		60	Ω

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ELECTRICAL CHARACTERISTICS (continued)

$V_{BAT} = 6$ to 28 V ; $T_J = -40$ °C to 150 °C (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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DIAGNOSTIC FUNCTIONS AND PROTECTION

$C_{maxd_{MIN}}$	Minimum dwell time capacitor		2.3			nF
$T_{D_{MAX}}$	Maximum dwell time	Maxdwell = 47 nF	50	94	130	ms
$I_{maxdwell}$	Maxdwell pin current for $T_{D_{MAX}}$		0.75	1.0	1.25	μA
V_{OVS}	Over voltage shutdown		29		35	V
T_{OVD}	Over voltage shutdown delay			13		μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

Input and Spike Filter

When the input signal voltage reaches V_{INH} , the IGBT will be switched on charging the coil. When the input voltage goes below V_{INL} , the coil current through the IGBT will be turned off. If the FAD1101B-F085 is in Maxwell mode, the input signal control is disabled. After an Maxwell sequence input control will be re-enabled after the input has reached a valid low. Positive and negative spikes of less than T_{spike} duration at the input line will be filtered out and will not turn on/off the IGBT.

Flag Output

The current sensing flag function communicates the IGBT collector current value to the main engine control device. The flag pin is an open drain output and requires an external pull up impedance to a nominal 5.0 V supply. Like the signal pin it has a protection clamp circuit which allows the flag to go up to 16 V before being activated.

A collector low and collector high current is detected and signaled at the flag pin. When the input is first enabled the flag pin is in a tri-state condition (or off). When the collector current reaches the specified low value the flag is enabled and goes low. The flag remains low until the collector current reaches the Collector high value at which time the flag is placed back in the tri-state condition (Figure 4).

Maximum Dwell Time and Hard-Shutdown (HSD)

When the IGBT is turned on, a delay timer, dependent on the value of the external Maxwell capacitor, is started. If a valid falling edge has not been received after the time T_{DMAX} , the IGBT will be turned off. The IGBT cannot be subsequently turned on until a valid rising edge is detected (Figure 5). If the Maxwell capacitor has a value of $< 2.3 \text{ nF}$ or the Maxwell pin is shorted to ground, the maximum dwell time functions will be disabled.

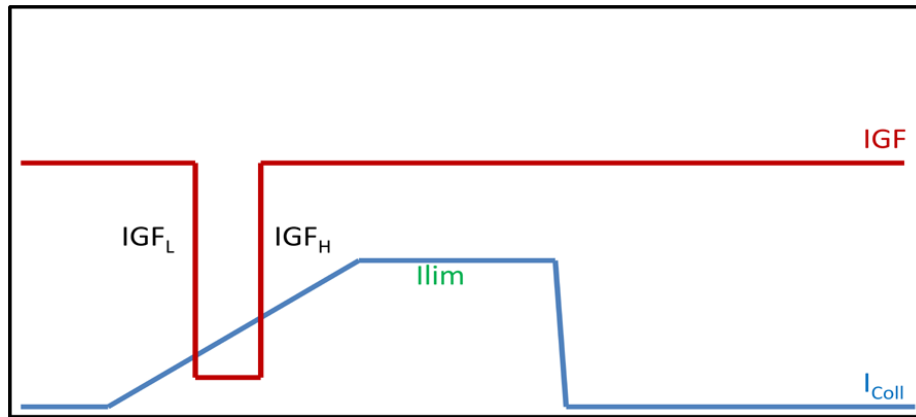


Figure 4. Current Limit and Flag Operation

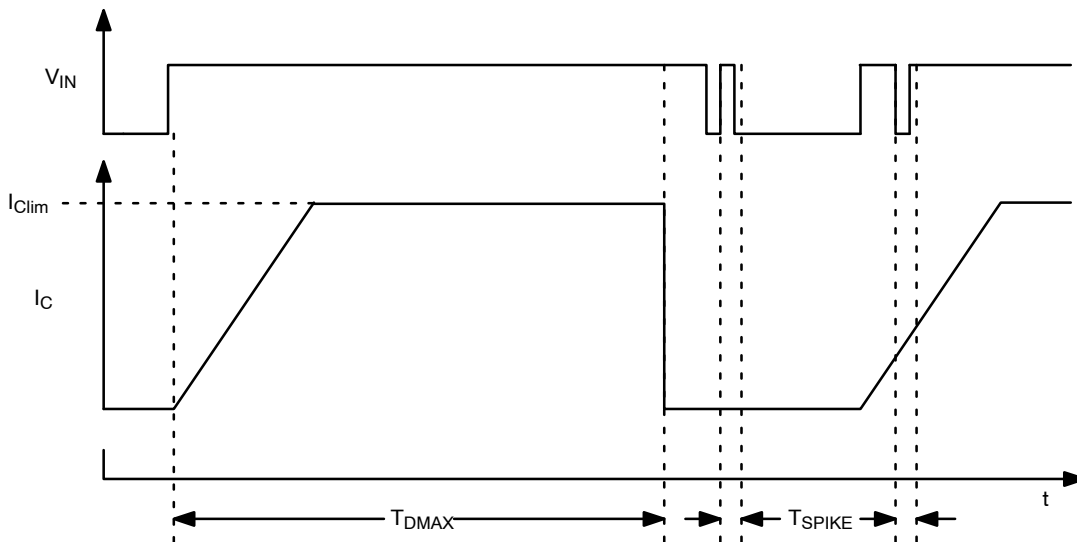


Figure 5. Dwell Time and Hard-Shutdown

Figure 6 shows the Relationship between the Maxwell capacitor and Max Dwell Time.

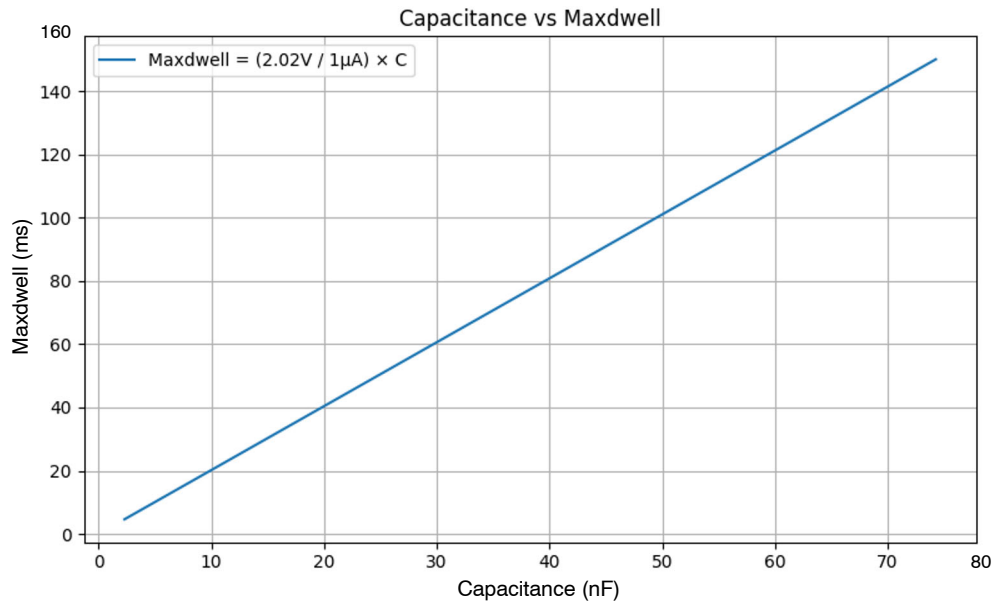


Figure 6. T_{DMAX} as Function of External Maxwell Capacitor

Over Voltage Protection

To protect the coil and the IGBT from stress due to over voltage at the battery line, the driver IC hard turns off its gate

output if the battery voltage remains above the Over Voltage Shutdown threshold for longer than T_{OVD} (typ. 13 μs).

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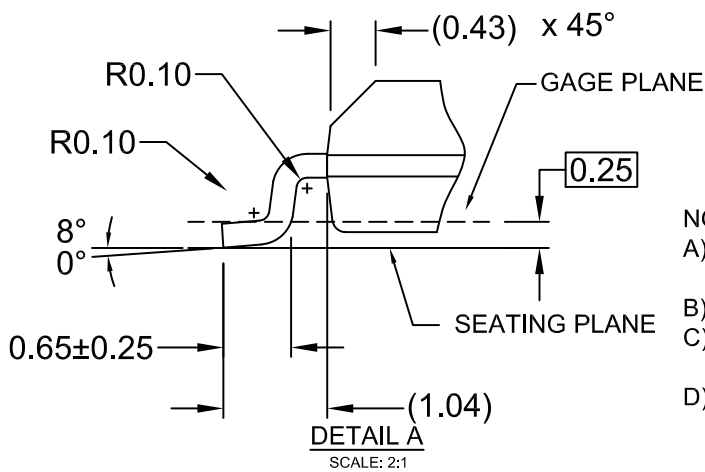
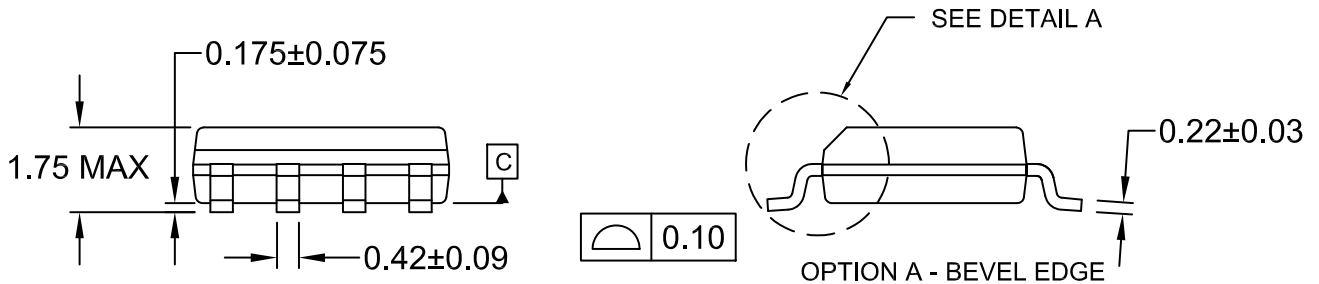
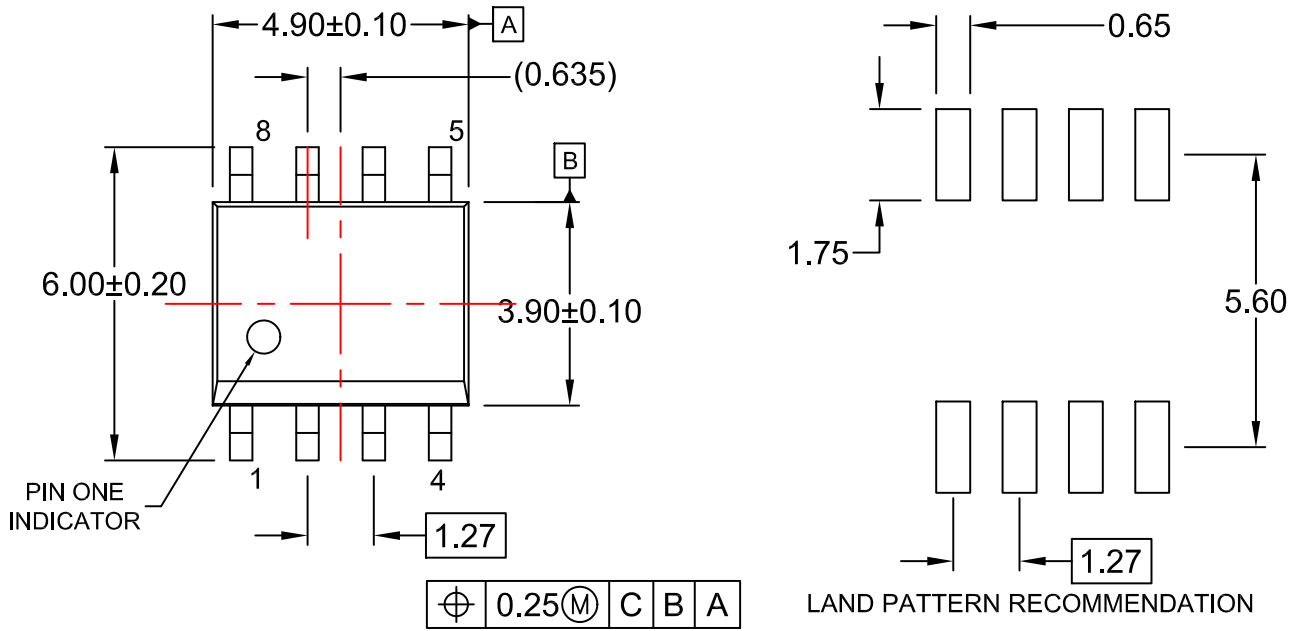
REVISION HISTORY

Revision	Description of Changes	Date
P0	Initial Preliminary document release.	10/22/2025

FAD1101B-F085

PACKAGE DIMENSIONS

SOIC8
CASE 751EB
ISSUE A



NOTES:

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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